

AEROSPACE MATERIAL SPECIFICATION

SAE

AMS 3731/5B

Issued 1 OCT 1981
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Superseding AMS 3731/5A

Submitted for recognition as an American National Standard

POTTING COMPOUND, EPOXY
Bisphenol A-Type
Filled, Room Temperature Cure, Low Exotherm

This specification has been declared "NONCURRENT" by the Aerospace Materials Division, SAE, as of July, 1992. It is recommended, therefore, that this specification not be specified for new designs.

This cover sheet should be attached to revision "A" of the subject specification.

"NONCURRENT" refers to those materials which have previously been widely used and which may be required on some existing designs in the future. The Aerospace Materials Division, however, does not recommend these as standard materials for future use in new designs. Each of these "NONCURRENT" specifications is available from SAE upon request.

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AN AMERICAN NATIONAL STANDARD



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AEROSPACE MATERIAL SPECIFICATION

Submitted for recognition as an American National Standard

AMS 3731/5A

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Superseding AMS 3731/5

POTTING COMPOUND, EPOXY Bisphenol A-Type Filled, Room Temperature Cure, Low Exotherm

1. SCOPE:

1.1 Form: This specification covers a filled, room-temperature-polymerizing epoxy resin formulation, supplied as a two-component system.

1.2 Application: Primarily for use as a potting or sealing material where a low coefficient of thermal expansion is desired.

2. APPLICABLE DOCUMENTS: See AMS 3731.

3. TECHNICAL REQUIREMENTS:

3.1 Basic Specification: The complete requirements for procuring the product described herein shall consist of this document and the latest issue of the basic specification, AMS 3731.

3.2 Material: Shall be an epoxy-based polymer with a filler and a curing agent.

3.3 Properties: The compound shall conform to the following requirements:

3.3.1 Mixed Uncured Compound: The compound, mixed in accordance with manufacturer's instructions, shall exhibit the following properties:

3.3.1.1 Viscosity: Shall be not greater than 10,000 centipoise (10.0 Pa•s) at 23°C (73°F), determined within 5 min. after mixing, using a Brookfield Model LVF viscometer and No. 3 spindle at 6 revolutions per minute.

3.3.1.2 Pot Life: Usable life of the compound, defined as the time to attain double the initial viscosity determined in 3.3.1.1, shall be not less than 45 min. at 23°C (73°F).

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3.3.1.3 Curing Time: The time required to develop the cured product properties specified in 3.3.2 shall be not more than 5 days at 23°C (73°F) or not more than 4 hr at 95°C (200°F).

3.3.7.4 Demold Time: The time required before the part can be removed from the mold and retain its integrity shall be not more than 24 hr at 23°C (73°F).

3.3.2 Cured Product: The compound, mixed and cured in accordance with manufacturer's instructions, shall exhibit the following properties, determined in accordance with test methods listed in AMS 3731:

3.3.2.1	Flexural Strength, min	11,500 psi (80 MPa)
3.3.2.2	Izod Impact Strength, per unit of notch, min	0.3 ft-lb per in. (16 J/m)
3.3.2.3	Compressive Strength, min	18,000 psi (725 MPa)
3.3.2.4	Insulation Resistance	
3.3.2.4.1	At 23°C (73°F), min	1x10 ⁶ megohms
3.3.2.4.2	At 720°C (250°F), min	7x10 ³ megohms
3.3.2.4.3	After hydrolytic stability conditioning, min	1x10 ⁴ megohms
3.3.2.5	Dielectric Constant at 1 KHz, max	5.5
3.3.2.6	Dissipation Factor at 1 KHz, max	0.04
3.3.2.7	Heat Deflection Temperature at 264 psi (1.8 MPa), min	74°C (165°F)
3.3.2.8	Coefficient of Linear Thermal Expansion, max	
3.3.2.8.1	From -54°C to +23°C (-65°F to +73°F)	35x10 ⁻⁶ mm/mm per deg C (20x10 ⁻⁶ in./in. per deg F)
3.3.2.8.2	From 23°C to 74°C (73°F to 165°F)	45x10 ⁻⁶ mm/mm per deg C (25x10 ⁻⁶ in./in. per deg F)
3.3.2.9	Water Absorption after 24 hr Immersion, max	0.25%
3.3.2.10	Specific Gravity, max	1.8